# SILICON TRANSISTOR 2SD2230

# NPN SILICON EPITAXIAL TRANSISTOR FOR LOW-FREQUENCY POWER AMPLIFIERS

The 2SD2230 is an element realizing ultra low  $V_{CE(sat)}$ . This transistor is ideal for muting such as stereo recorders, VCRs, and TVs.

### **FEATURES**

NEC

• Low VCE(sat):

 $\begin{array}{l} V_{CE(sat)1} = 33 \mbox{ mV TYP}. \ @ \mbox{ lc} = 100 \mbox{ mA}, \mbox{ lb} = 10 \mbox{ mA} \\ V_{CE(sat)2} = 150 \mbox{ mV TYP}. \ @ \mbox{ lc} = 500 \mbox{ mA}, \mbox{ lb} = 20 \mbox{ mA} \end{array}$ 

• High hFE and high current

# QUALITY GRADES

Standard

Please refer to "Quality Grades on NEC Semiconductor Devices" (Document No. C11531E) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

# ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

| Parameter                    | Symbol | Ratings     | Unit |
|------------------------------|--------|-------------|------|
| Collector to base voltage    | Vсво   | 16          | V    |
| Collector to emitter voltage | VCEO   | 16          | V    |
| Emitter to base voltage      | Vebo   | 5           | V    |
| Collector current (DC)       | ID(DC) | 500         | mA   |
| Total power dissipation      | Рт     | 200         | mW   |
| Junction temperature         | Tj     | 150         | °C   |
| Storage temperature          | Tstg   | –55 to +150 | °C   |

#### 2.6±0.2 2.6±0.2 0.65<sup>±0.1</sup> 0.65<sup>±0.1</sup>

PACKAGE DRAWING (UNIT: mm)

Electrode connection

- 1. Emitter (E)
- 2. Base (B)
- 3. Collector (C)
- Marking: D46

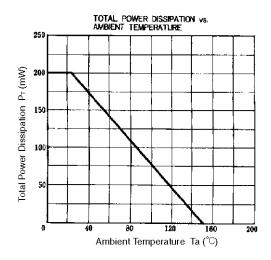
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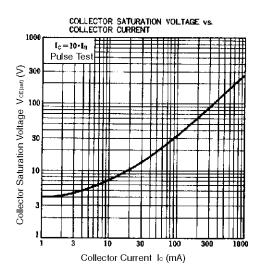
# ELECTRICAL CHARACTERISTICS (Ta = 25°C)

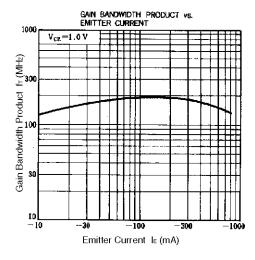
| Parameter                    | Symbol                | Conditions  | MIN. | TYP. | MAX. | Unit |
|------------------------------|-----------------------|---|------|------|------|------|
| Collector cutoff current     | Ісво                  | V <sub>CB</sub> = 16 V, I <sub>E</sub> = 0                |      |      | 100  | nA   |
| Emitter cutoff current       | Іево                  | VEB = 6.0 V, Ic = 0                                       |      |      | 100  | nA   |
| DC current gain              | hfe1*                 | $V_{CE} = 1.0 \text{ V}, \text{ I}_{C} = 100 \text{ mA}$  | 200  |      |      | -    |
| DC current gain              | hfe2*                 | $V_{CE} = 1.0 \text{ V}, \text{ Ic} = 500 \text{ mA}$     | 200  |      |      | -    |
| DC base voltage              | V <sub>BE</sub> *     | $V_{CE} = 1.0 \text{ V}, \text{ I}_{C} = 10 \text{ mA}$   | 550  |      | 700  | mV   |
| Collector saturation voltage | V <sub>CE(sat)1</sub> | Ic = 100 mA, Iв = 10 mA                                   |      | 33   | 50   | mV   |
| Collector saturation voltage | VCE(sat)2             | Ic = 500 mA, Iв = 20 mA                                   |      | 150  | 200  | mV   |
| Output capacitance           | Cob                   | V <sub>CB</sub> = 10 V, I <sub>E</sub> = 0, f = 1.0 MHz   |      |      | 15   | pF   |
| Gain bandwidth product       | f⊤                    | $V_{CE} = 1.0 \text{ V}, \text{ I}_{E} = -100 \text{ mA}$ | 50   |      |      | MHz  |

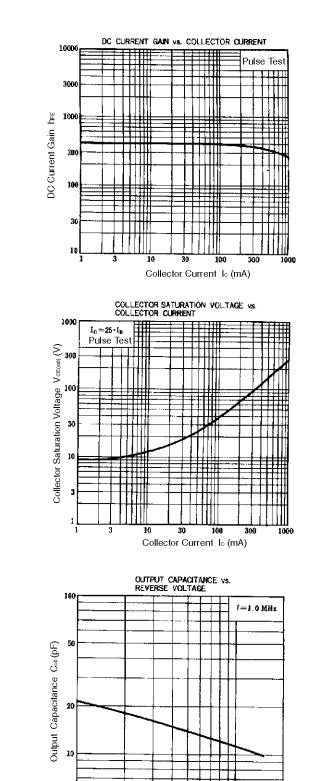
\* Pulse test PW  $\leq$  350  $\mu$ s, duty cycle  $\leq$  2%

# **TYPICAL CHARACTERISTICS (Ta = 25°C)**









2 5 10 Collector To Base Voltage Vos (V)

T

20

5

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# **RECOMMENDED SOLDERING CONDITIONS**

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact an NEC sales representative.

## Surface Mounting Type

For details of the recommended soldering conditions, refer to the document **Semiconductor Device Mounting Technology Manual** (C10535E).

| Soldering Method | Soldering Conditions  | Recommended<br>Condition Symbol |
|------------------|---|---------------------------------|
| Infrared reflow  | Package peak temperature: 230°C, Time: 30 sec. max. (at 210°C or higher),<br>Count: Once, Exposure limit: None* | IR30-00                         |
| VPS              | Package peak temperature: 215°C, Time: 40 sec. max. (at 200°C or higher),<br>Count: Once, Exposure limit: None* | VP15-00                         |
| Partial heating  | Pin temperature: 300°C max., Time: 10 sec. max. Exposure limit: None*   | 0                               |

\* After opening the dry pack, store it at 25°C or less and 65% RH or less for the allowable storage period.

#### Caution Do not use different soldering methods together (except for partial heating).

[MEMO]

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